



# Accelerate Innovation X14 Server Solutions

*Supporting Intel® Xeon® 6 processors*





# INTRODUCING SUPERMICRO X14 GENERATION



## The Supermicro X14 Advantage

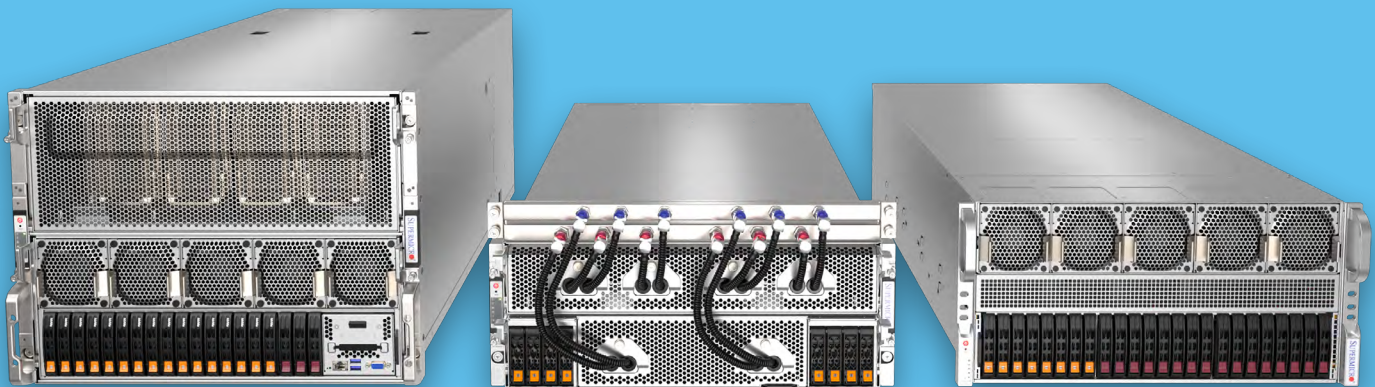
*The latest generation of proven platforms designed for maximum performance, efficiency and flexibility for AI, Cloud, Storage and 5G/Edge workloads*

### Supermicro Total IT Solutions

- Industry's broadest portfolio of systems based on Intel® Xeon® 6 processors
- Rack Scale plug-and-play service to deliver complete, validated solutions within weeks, not months
- Production capacity of up to 5,000 racks per month worldwide
- Made in the USA program with manufacturing in San Jose headquarters
- Industry standard compliance for hardware and silicon Root of Trust (RoT) and cryptographical attestation of components throughout the entire supply chain
- Supermicro liquid cooling including CPU/GPU cold plate, Cooling Distribution Unit and Cooling Distribution Manifolds for a complete integrated solution

### Optimized, Open Architectures

- More than 15 families of systems optimized for AI, Cloud, 5G Edge and more
- Modular Building Block architecture enables customization for specific workloads and configurations
- Resource saving architecture to reduce materials and energy usage
- Enhanced thermal capacity to support next-gen CPUs, GPUs and other components
- Flexible networking with Advanced I/O Modules (AIOM) up to 400G per card
- High ambient temperature operation up to 40°C with liquid cooling options
- Support for open and industry standards including OCP 3.0, DC-MHS, OAM, ORV2, OSF, Open BMC and EDSFF



**8U 8-GPU System**

**4U Liquid-cooled 8-GPU**

**5U 8-10 PCIe GPU**



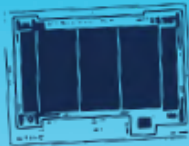
# ACCELERATE EVERYTHING WITH INTEL® XEON® 6 PROCESSORS



## What's New in Supermicro X14



New Intel® Xeon® 6 Processors



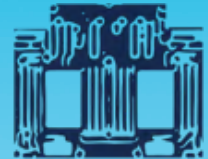
Higher core-count for greater compute density



Faster memory bandwidth. New capabilities to extend capacity



EDSFF E1.S and E3.S NVMe support



Data Center Modular Hardware System

### Intel® Xeon® 6700 series processors with E-cores

- Maximum performance-per-watt and core density for cloud, networking, analytics and scale-out workloads
- Up to 144 cores (144 threads) per CPU
- Up to 330W per CPU
- 1 or 2 socket servers
- 8 channel memory
- 6400 MT/s DDR5
- Up to 88 PCIe 5.0 lanes

#### Rack Density

up to **2.5x**

vs 4th Gen Intel® Xeon® <sup>1</sup>

#### Performance-Per-Watt

up to **2.4x**

vs 4th Gen Intel® Xeon® <sup>1</sup>

### Supermicro X14 systems will also support Intel® Xeon® 6700 with P-cores in Q1'25"

- Maximum performance-per-core for AI, HPC, storage and Edge workloads
- Up to 86 cores (172 threads) per CPU
- Up to 350W per CPU
- 1, 2, 4 or 8 socket servers
- 8 channel memory
- 6400 MT/s DDR5
- 8000 MT/s MCR DIMM
- Up to 88 PCIe 5.0 lanes with up to 136 lanes for 1S designs

<sup>1</sup> Compared to 4th Gen Intel Xeon Scalable Processors. Based on architectural projections as of August 21, 2023 relative to prior generation. Your results may vary.

# X14 UNIVERSAL GPU

Maximum acceleration for AI Training, LLMs, and Generative AI



Next-generation architecture for the most intensive AI workloads

Most comprehensive AI building block platform

Up to 8 OAM/SXM GPUs

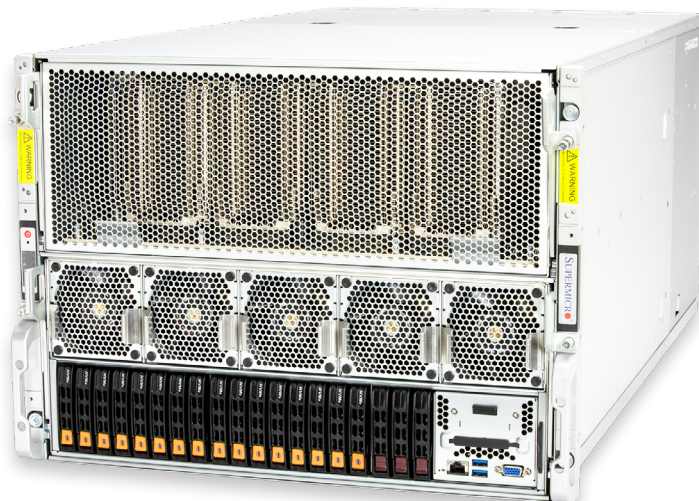
Up to 10 PCIe 5.0 slots

Support for DDR5-6400

8 hot-swap 2.5" NVMe drives

Direct-to-chip CPU and GPU liquid cooling options

**8 OAM/SXM GPUs in 8U,  
8 2.5" NVMe**



SYS-822GA-NBRT  
(Coming Soon!)

**8 OAM/SXM GPUs (liquid cooled) in 4U,  
8 2.5" NVMe**



SYS-422GA-NBRT-LCC  
(Coming Soon!)

## Open, Modular, Standards-Based Universal GPU System

Supermicro X14 Universal GPU systems feature an open, modular, standards-based architecture designed for maximum flexibility. Support for multiple industry-standard GPUs allows organizations to take advantage of different GPU configurations based on workload while only deploying a single server architecture, reducing infrastructure complexity and simplifying future upgrades.

Designed for serviceability with hot-swappable, tool-less components in a modular construction, the chassis are optimized for thermal capacity, supporting the latest generation of GPUs up to 700W TDP.

## Key Applications

- Large-scale AI Training
- Large Language Models
- AI/Deep Learning Training
- Industrial Automation
- Conversational AI
- Drug Discovery
- Climate and Weather Modeling
- Finance & Economics

# X14 PCIe GPU

Flexible configurations for AI training, Media, 3D Design, and Simulation



Up to double-width 10 PCIe GPUs

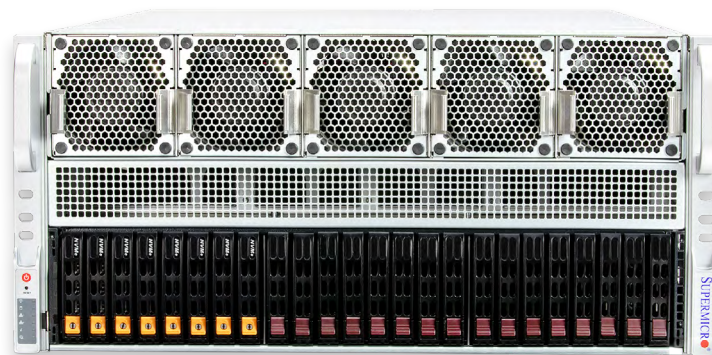
Up to 13 PCIe 5.0 slots

Support for DDR5-6400

Up to 16 NVMe drives + 8 SATA drives

Direct-to-chip CPU and GPU liquid cooling options

**Up to 10 Double-width PCIe GPUs in 5U  
16 2.5" NVMe + 8 2.5" SATA**



SYS-522GA-NRT  
(Coming Soon!)

AIOM  
Ready

## Flexible Platform

Optimized for the next generation of HPC, action-oriented AI, 3D simulation, and advanced graphic design and rendering, Supermicro X14 PCIe accelerated solutions empower the creation of 3D worlds, digital twins, 3D simulation models and the Metaverse.

These systems support next-generation accelerators based on the industry-standard PCIe form factor, with up to 10 double-width GPUs in a 5U chassis. Additional networking slots provide connectivity of up to 400Gb/s to create high performance clusters of up to 32 nodes, while optional direct-to-chip liquid cooling is available to deliver superior efficiency for the most demanding performance.

## Key Applications

- AI Model Training
- Digital Twins
- 3D Simulation
- Real-time Ray-tracing
- Animation and Modeling
- Cloud Gaming
- Design & Visualization
- 3D Rendering
- VDI
- Media/Video Streaming
- Diagnostic Imaging

# X14 8U SUPERBLADE®

## Highest Density Multi-Node Server Solutions



120 servers per rack (Up to 34,560 CPU cores)

8U enclosure with 20 single-wide or 10 double-wide servers, sharing power supplies, cooling fans, CMMs, Ethernet, and InfiniBand switches

Dual Intel® Xeon® 6700 series processors with E-cores - up to 288 cores per node

Support for DDR5-6400 with up to 16 DIMMs (up to 4TB memory)

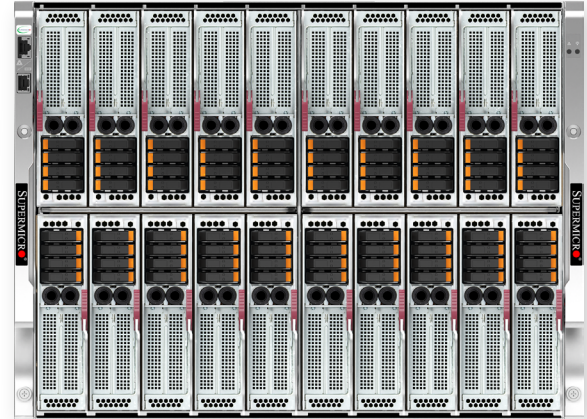
5 NVMe SSDs (4 E1.S and 1 M.2)

400G IB or Ethernet (OCP 3.0), 200G integrated IB switch, and up to 4x 25G Ethernet switches

Reusable enclosure, power supplies, cooling fans, CMMs, and switches for future generation servers

96% efficiency, (N+N / N+1) redundant power supplies.

Direct liquid cooling option



### 20 DP Nodes in 8U



SBI-422B-1NE14

16 DIMMs, 4 E1.S, 1 M.2

### 10 DP Nodes in 8U



SBI-422B-5NE14

16 DIMMs, 4 E1.S, 1 M.2

## Future-proof, Resource-saving Architecture

Supermicro's high-performance, density-optimized, and energy-efficient SuperBlade® can significantly reduce initial capital and operational expenses for many organizations. SuperBlade® utilizes shared, redundant components, including power supplies, cooling fans, chassis management modules (CMMs), switches, or pass-thru modules to deliver the most cost-effective, green computing solutions.

The X14 8U SuperBlade® architecture maximizes rack density, with up to 120 dual-processor servers in a 48 rack. Cable reduction can be up to 95% when compared to rackmount servers. Optional direct liquid cooling (DLC) can support servers with the highest power CPUs to achieve the lowest PUE with the best TCO.

## Key Applications

- AI Inferencing
- Hybrid and Private Cloud
- Cloud Computing
- Big Data Analytics
- Financial Services
- HPC
- CDN
- vSAN

# X14 6U SUPERBLADE®

Memory-Optimized Multi-Node Architecture for EDA and Enterprise Applications



100 servers per rack (Up to 28,800 CPU cores)

6U enclosure with 10 single-wide or 5 double-wide servers, sharing power supplies, cooling fans, CMMs, and Ethernet switches

1 or 2 Intel® Xeon® 6700 series processors with E-cores - up to 288 cores per node

Support for DDR5-6400 with 32 DIMMs in DP or 16 DIMMs in UP

Up to 10 NVMe SSDs

Up to 4 GPUs or network cards

400G IB or Ethernet (PCIe 5.0 x16 slots), and up to 4x 25G Ethernet switches with 100G uplinks

Reusable enclosure, power supplies, cooling fans, CMMs, and switches for future generation servers

96% efficiency, (N+N / N+1) redundant power supplies

Direct liquid cooling option



## 6U SuperBlade® – 10/5 UP Nodes in 6U



SBI-612B-1C2N

16 DIMMs, 2 SAS/NVMe, 1 M.2



SBI-612B-1NE34  
SBI-612B-5NE34

16 DIMMs, 4 E3.S, 1 M.2

## 6U SuperBlade® – 10/5 DP Nodes in 6U



SBI-622B-1NE34  
SBI-622B-5NE34

32 DIMMs, 4 E3.S, 2 M.2 via Adapter



SBI-622B-1NE38  
SBI-622B-5NE38

32 DIMMs, 8 E3.S, 2 M.2 via Adapter

## Future-proof, Resource-saving Architecture

Supermicro's X14 6U high-performance, density-optimized, and energy-efficient SuperBlade® can significantly reduce initial capital and operational expenses for many organizations. SuperBlade® utilizes shared, redundant components, including power supplies, cooling fans, chassis management modules (CMMs), switches, or pass-thru modules to deliver the most cost-effective, green computing solutions.

The X14 6U SuperBlade® architecture maximizes rack density, with up to 100 servers per rack. Optional direct liquid cooling (DLC) can support servers with the highest power CPUs to achieve the lowest PUE with the best TCO.

Supermicro's X14 6U SuperBlade® architecture is optimized for performance with maximum capacity (32 DIMMs – DP, 16 DIMMs - UP). 20 GPUs can be installed in 6U enclosures for AI/ML, acceleration, graphics, and 3D rendering. 10 NVMe SSDs per server is perfect for vSAN, big data analytics, and financial services.

## Key Applications

- AI/ML Inferencing
- Hybrid and Private Cloud
- Cloud Computing
- Big Data Analytics
- Financial Services
- HPC
- CDN
- vSAN
- EDA

# X14 HYPER

## Best-in-class Performance and Flexibility Rackmount Server



Single and dual socket configurations supporting Intel® Xeon® 6700 series processors with E-cores

Support for DDR5-6400 with up to 32 DIMMs per system

All-hybrid hot-swappable NVMe/SAS/SATA; up to 24 drive bays

Flexible networking options with up to 2 AIOM networking slots (OCP NIC 3.0 compatible)

Optional PCIe slot configurations up to 8 PCIe 5.0 x8 or 4 PCIe 5.0 x16 slots with support for double-width GPU/Accelerator cards

Optional direct-to-chip liquid cooling

Redundant Titanium level (96%) from 900W to 2600W



SYS-122H-TN

AIOM  
Ready

1U DP Hyper (SP)



SYS-122H-TN

Up to 12 2.5" NVMe/SAS/SATA

2U DP Hyper (SP)



SYS-222H-TN

8 to 24 2.5" NVMe/SAS/SATA

2U DP Hyper (AP)



SYS-222HA-TN

8 to 24 2.5" NVMe/SAS/SATA  
(Coming Soon!)

1U UP Hyper (SP)



SYS-112H-TN

Up to 12 2.5" NVMe/SAS/SATA

2U UP Hyper (SP)



SYS-212H-TN

8 to 24 2.5" NVMe/SAS/SATA

### Flagship Performance and Flexibility for Enterprise Data Centers

The new X14 Hyper series brings next-generation performance to Supermicro's range of rackmount servers, built to take on the most demanding workloads in the most proven 1U and 2U form factors. Our modular design allows customization on storage, expansion slot, network and power supplies to meet the applications requirements. Gracefully balances compute, storage and expansion in a tool-less rackmount design for optimization as well as flexibility and serviceability.

The X14 Hyper lineup includes the best-selling dual-socket configurations designed for maximum power and compute density, as well as new single-socket architectures to provide balanced performance with only one processor.

### Key Applications

- Enterprise Server
- Cloud Computing
- Big Data Analytics
- Hyperconverged Storage
- AI Inference and Machine Learning
- Network Function
- Virtualization





# X14 HYPER-E

Maximum Performance and Flexibility for Edge Data Centers



Dual Intel® Xeon® 6700 series processors with E-cores

High-density processing power in compact form factors suitable for Edge deployments

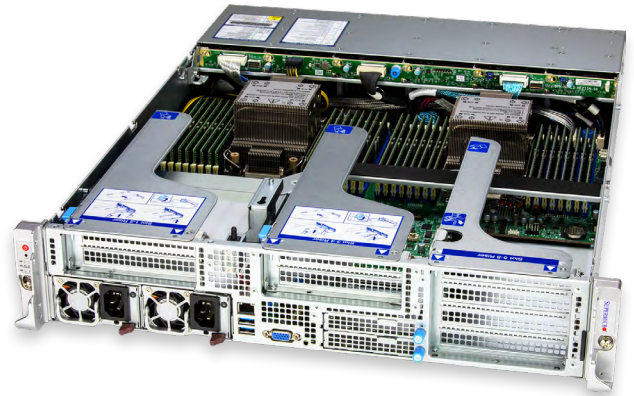
Support for DDR5-6400 with up to 32 DIMMs

Flexible I/O with up to 2 AIOM PCIe 5.0 and 8 PCIe 5.0 slots

Both AC and DC power configurations available with redundant power supplies

Enhanced operating temperatures from -5°C to 55°C (CPU TDP-dependent)

Front or rear I/O configurations available



SYS-222HE-FTN

AIOM  
Ready

2U DP Hyper-E



SYS-222HE-TN  
Rear I/O

2U DP Hyper-E



SYS-222HE-FTN  
Front I/O

## Data Center Performance at the Edge

Hyper-E delivers the performance and flexibility of Supermicro's flagship rackmount server family in a compact form factor optimized for telco and micro data center deployments.

A mid-depth chassis and front I/O makes it easier to incorporate Hyper-E into existing edge and telco infrastructure, while carrier grade (NEBS Level 3) design and

optional DC power options further enhance flexibility in non-traditional data center environments.

Storage and expansion configurations can be adjusted depending on the application, while maintenance-friendly design innovations eliminate the need for tools when servicing the system to simplify rollout and installation.

## Key Applications

- 5G Core and Edge
- Telco Micro Data Center

# X14 BIGTWIN®

## Industry-leading Multi-node Architectures



Highly configurable 2U 4-node and 2U 2-node systems optimized for density or storage

Optimized thermal design for dual socket Intel® Xeon® 6700 series processors with E-cores

Optional direct-to-chip liquid cooling can provide increased thermal capacity without sacrificing expansion slots

Support for DDR5-6400 with up to 16 DIMMs per node

All-hybrid hot-swappable NVMe/SAS/SATA drive bays and new E3.S configuration for increased storage density

Flexible networking with up to 400G Ethernet per node

Supports a range of power supply capacities from 2200W to 3600W

### 2U 4-Node BigTwin®



SYS-222BT-H Series

AIOM  
Ready

2U 2-Node BigTwin



SYS-622BT-D Series

2U 2-Node BigTwin



SYS-222BT-D Series

2U 4-Node BigTwin



SYS-622BT-H Series

2U 4-Node BigTwin



SYS-222BT-H Series

### Highly Modular Multi-Node Systems with Tool-Less Design

Supermicro X14 BigTwin® systems provide superior performance and serviceability with dual Intel® Xeon® 6 processors (Formerly codenamed Sierra Forest and Granite Rapids) per node and hot-swappable tool-less design.

Optimized for density (2U4N) or storage (2U2N), BigTwin® architectures can be more cost effective than standard 1U servers thanks to shared power and cooling while also increasing compute density and reducing overall TCO. The modular mid-plane design provides NVMe Gen 5 storage controller options and a new riser card design can support up to 4 M.2 drives for boot/OS or metadata/caching.

### Key Applications

- HCI
- HPC
- CDN
- Hybrid Cloud Container-as-a-Service
- Cloud Computing
- Big Data Analytics
- Back-up and Recovery
- Scale-Out Storage



# X14 GRANDTWIN®

## Multi-Node Architecture Optimized for Single-Processor Performance



Single socket per node supporting Intel® Xeon® 6700 series processors with E-cores

Support for DDR5-6400 with up to 16 DIMMs per node

Flexible PCIe, storage, and AIOM configurations to suit a wide range of application requirements

Front I/O configuration to simplify cold-aisle servicing

Optional support for EDSSD E1.S NVMe drives

### 2U 4-Node GrandTwin®



SYS-212GT-HNF (Front View)

AIOM  
Ready

2U 4-Node GrandTwin® (Front I/O)



SYS-212GT-HNF

2U 4-Node GrandTwin® (Rear I/O)



SYS-212GT-HNR

### Highly Configurable Single Processor Systems with Front or Rear I/O

The GrandTwin® architecture is an all-new architecture purpose-built for single-processor performance. The design maximizes compute, memory and efficiency to deliver maximum density. Powered by Intel® Xeon® 6 processors, GrandTwin's flexible modular design can be easily adapted for a wide range of applications, with the ability to add or remove components as required, reducing cost.

For front configurations, all I/O and node trays are fully accessible from the cold aisle, simplifying installation and servicing in space-constrained environments. Flexible storage and networking options are available via front AIOM modules, allowing countless custom configurations.

### Key Applications

- MEC (Multi-Access Edge Computing)
- HPC
- Cloud Gaming
- Multi-Purpose CDN
- High-Availability Cache Cluster
- Telco Edge Cloud
- EDA (Electronic Design Automation)
- Mission-Critical Web Applications

# X14 CLOUDDC WITH DC-MHS

All-in-one Rackmount Platform for Cloud Data Centers Designed to OCP DC-MHS Specifications



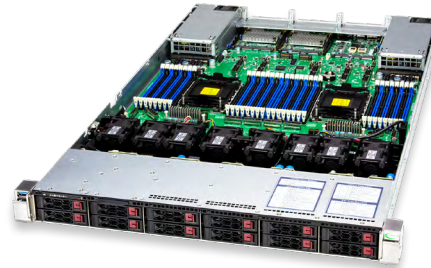
Single and dual socket configurations supporting Intel® Xeon® 6700 series processors with E-cores

Support for DDR5-6400 with up to 32 DIMMs per node

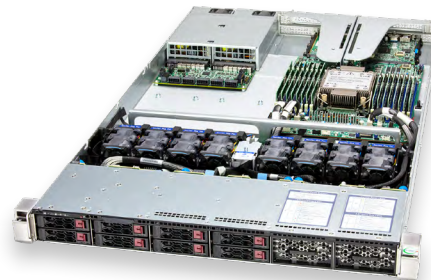
Modular OCP DC-MHS support to reduce complexity and simplify servicing in large-scale data center deployments

U.2 NVMe/SAS/SATA drives with all-hybrid options

Support for PCIe 5.0 and CXL 2.0



SYS-122C-TN



SYS-112C-TN

AIOM Ready

1U DP CloudDC (SP)



SYS-122C-TN  
Up to 12 hot-swap NVMe

2U DP CloudDC (SP)



SYS-222C-TN  
Up to 24 hot-swap NVMe

1U UP CloudDC (SP)



SYS-112C-TN  
Up to 12 hot-swap NVMe

## High-density, Tool-less Mechanical Design for Rapid Cloud Deployment and Easy Maintenance

The new Supermicro X14 CloudDC with DC-MHS delivers ultimate flexibility on I/O and storage to support a range of cloud and data center workloads. The systems are designed to meet OCP DC-MHS specifications, improving modularity and flexibility for large-scale enterprises and cloud service providers to simplify data center management with DC-SCM modules. X14 CloudDC also features tool-less brackets, hot-swap drive trays and redundant power supplies that ensure a rapid deployment and more efficient maintenance in data centers. High-efficiency Titanium Level redundant power supplies provide resiliency and low carbon footprint. Rich security features include Intel® SGX, TPM 2.0, signed firmware, Silicon Root of Trust, Secure Boot, System Erase, Runtime FW protection, FIPS Compliance and Trusted Execution Environment.

## Key Applications

- Private/Public/Hybrid Cloud
- Cloud Computing
- Big Data Analytics
- AI Inference
- Machine Learning
- Network Appliance
- Virtualization
- Open BMC
- ODM Custom Design for CSP/Hyperscalers



# X14 UP WIO

Industry's Widest Variety of I/O Optimized Servers



Single Intel® Xeon® 6700 series processors with E-cores

Support for DDR5-6400 with up to 8 DIMMs

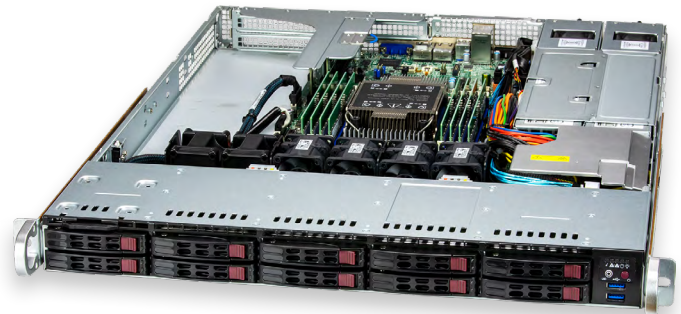
U.2 NVMe/SAS/SATA drives with up to 8 hybrid drives

Support for PCIe 5.0 and CXL 2.0

Native SATA support on motherboard; no additional controller card required

Supports double-width GPU/FPGA cards in both 1U and 2U

1U WIO with 4 PCIe Slots



SYS-112B-WR

*AIOM Ready*

1U UP WIO



SYS-112B-WR

1U UP WIO



SYS-512B-WR

2U UP WIO



SYS-522B-WR

## Wide-Ranging Flexibility for any Enterprise Workload

Supermicro WIO systems offer a wide range of I/O options to deliver truly optimized systems for specific requirements. Users can optimize the storage and networking alternatives to accelerate performance, increase efficiency and find the perfect fit for their applications. In addition to enabling customizable configurations and optimization for multiple application requirements, Supermicro WIO SuperServers® also provide attractive cost advantages and investment protection.

## Key Applications

- Enterprise Applications
- Networking Appliance
- Firewall/Security Appliances
- General Purpose Computing
- Cloud Computing
- Media Entertainment

# X14 PETASCALE ALL-FLASH EDSFF

Maximum Throughput and Density with EDSFF Drive and CXL 2.0 Support



- Dual Intel Xeon 6700 series processors with E-cores
- Support for DDR5-6400 with up to 32 DIMMs
- Up to 32 EDSFF E3.S drives in 2U or 16 E3.S drives in 1U
- Up to 1.92PB of NVMe storage in 2U or 960TB in 1U
- Up to 8 Type 3 CXL modules
- Symmetrical architecture to reduce latency
- OCP Data Center Modular Hardware System (DC-MHS) support



SSG-222B-NE3X24R

1U High Density All-Flash



SSG-122B-NE316R

16 EDSFF E3.S (1T) NVMe SSD

2U High Density All-Flash with CXL



SSG-222B-NE3X24R

Up to 32 EDSFF E3.S (1T) NVMe SSD

## Highest Performance 1U and 2U All-Flash Servers

The AI revolution is using and generating massive amounts of data and these workloads require application-specific architectures at every stage of the data pipeline. Supermicro's flagship X14 Petascale storage platform offers the best architecture to drive large-scale, data-intensive AI and HPC workloads, offering industry-leading memory bandwidth using up to eight Type 3 CXL modules. With up to 32 E3.S drives in 2U and unprecedented end-to end PCIe Gen5 performance, new X14 Petascale systems can help organizations to reach their performance and capacity goals with greater rack density than ever before.

The new Intel Xeon 6 processors support the latest PCIe Gen 5 standard to handle the high throughput of a large number of NVMe drives and get the maximum performance out of the new Gen 5 E3.S drives, as well as CXL 2.0 on all device types to maximize memory capacity for in-memory database applications.

## Key Applications

- Data Intensive HPC/AI
- Private & Hybrid Cloud
- Software-Defined Storage
- NVMe Over Fabrics Solution
- In-Memory Computing
- Composable Infrastructure Platform



# X14 TELCO/EDGE

Compact and short-depth rackmount systems for telco Edge deployments



Single Intel® Xeon® 6700 series processors with E-cores

High-density processing power in compact form factors suitable for Edge deployments

Flexible I/O with up to 3 PCIe 5.0 slots in 1U or 4 slots in 2U

Both AC and DC power configurations available with redundant power supplies

Enhanced operating temperatures from -5°C to 55°C (CPU TDP-dependent)



SYS-112B-FWT

**AIOM**  
Ready

1U UP Short-Depth



SYS-112B-FWT  
SYS-112B-FDWR

2U UP Short-Depth



SYS-212B-FN4TP

## Optimized Designs for 5G, Edge Computing and Emerging IoT Systems

Supermicro provides innovative and first-to-market technologies that are the building blocks for today's embedded computing platforms. Rapid growth in embedded markets and open standards are driving the need for higher levels of product integration and optimization through virtualization, AI inferencing, network connectivity, remote management, mobile communication, expanded I/O, and device-to-device communications using space and power efficient configurations.

Supermicro's family of high-performance embedded products are optimized for a wide range of applications and solutions. Supermicro offers many flexible and customized solutions for critical OEM projects, as well as advanced designs for stringent environments, firmware customization, BOM enhancements, and a wide range of legacy IO support.

## Key Applications

- Multi-Access Edge Computing
- Flex-RAN/Open RAN
- Edge AI Outdoor 5G

# X14 HYPER

1U DP Hyper

2U DP Hyper

1U UP Hyper

2U UP Hyper

**NEW!**

Intel® Xeon® 6 Processors Supported



MODEL	SYS-122H-TN	SYS-222H-TN	SYS-112H-TN	SYS-212H-TN
Processor Support	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache per CPU	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache per CPU	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache
Serverboard	SUPER® X14DBM-SP	SUPER® X14DBM-SP	SUPER® X14SBH	SUPER® X14SBH
Chipset	System on Chip	System on Chip	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 32 DIMM slots Max Memory (1DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 2TB 5200MT/s ECC DDR5 RDIMM	Slot Count: 32 DIMM slots Max Memory (1DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 2TB 5200MT/s ECC DDR5 RDIMM	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 1TB 5200MT/s ECC DDR5 RDIMM	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 1TB 5200MT/s ECC DDR5 RDIMM
Expansion Slots	Default 1 PCIe 5.0 x16 FHHL slot(s) 2 PCIe 5.0 x16 FH/10.5"L slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Option A* • 4 PCIe 5.0 x16 FH/10.5"L double-width slot(s) • 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible) • 1 PCIe 5.0 x8 AIOM slot(s) (OCP 3.0 compatible) Option B* • 8 PCIe 5.0 x8 (in x16) FH/10.5"L slot(s) • 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible) • 1 PCIe 5.0 x8 AIOM slot(s) (OCP 3.0 compatible)	Default • 1 PCIe 5.0 x16 FHHL slot(s) • 1 PCIe 5.0 x16 FHFL double-width slot(s) • 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Option A • 1 PCIe 5.0 x16 FHFL double-width slot(s) • 1 PCIe 5.0 x16 FH/10.5"L double-width slot(s) Option B • 1 PCIe 5.0 x16 FHFL double-width slot(s) • 2 PCIe 5.0 x8 FH/10.5"L slot(s)
Connectivity	Via AIOM	Via AIOM	Via AIOM	Via AIOM
VGA/Audio	1 VGA port(s)	1 VGA port(s)	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS; Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS; Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS; Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS; Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 8 bay(s) 8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) Option A: Total 12 bay(s) 12 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110)	Default: Total 8 bay(s) • 8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) Option A: Total 16 bay(s) • 16 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) Option B: Total 24 bay(s) • 24 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110)	Default: Total 8 bay(s) • 8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) Option A: Total 12 bay(s) • 8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) • 4 front hot-swap 2.5" SAS*/SATA* drive bay(s) *Optional M2: 2 M.2 NVMe/SATA slot(s) (M-key 2280/22110/25110; VROC required for RAID)	Default: Total 8 bay(s) • 8 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) Option A: Total 16 bay(s) • 8 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) • 8 front hot-swap 2.5" SAS*/SATA* drive bay(s) Option B: Total 16 bay(s) • 16 front hot-swap 2.5" SAS*/SATA* drive bay(s) Option C: Total 24 bay(s) • 24 front hot-swap 2.5" SAS*/SATA* drive bay(s) *Optional M2: 2 M.2 NVMe/SATA slot(s) (M-key 2280/22110/25110)
Power Supply	2x 1200W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 1200W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 1200W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 1200W Redundant (1 + 1) Titanium Level (96%) power supplies
Cooling System	8 counter-rotating 40x40x56mm Fan(s)	4 counter-rotating 80x80x38mm Fan(s)	8 counter-rotating 40x40x56mm Fan(s)	6 counter-rotating 60x60x56mm Fan(s)
Form Factor	1U Rackmount	2U Rackmount	1U Rackmount	2U Rackmount



# X14 HYPER-E

2U DP Hyper-E

2U DP Hyper-E



MODEL	SYS-222HE-TN	SYS-222HE-FTN
Processor Support	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/288T; Up to 108MB Cache per CPU	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/288T; Up to 108MB Cache per CPU
Serverboard	SUPERMICRO® X14DBM-SP	SUPERMICRO® X14DBM-SP
Chipset	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 32 DIMM slots Max Memory (1DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 2TB 5200MT/s ECC DDR5 RDIMM	Slot Count: 32 DIMM slots/16 Channels Max Memory (1DPC): Up to 2 TB 6400MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 2 TB 5200MT/s ECC DDR5 RDIMM
Expansion Slots	Option A* 3 PCIe 5.0 x16 (in x16) FH/10.5"L double-width slot(s) 1 PCIe 5.0 x16 (in x16) FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible) Option B* 6 PCIe 5.0 x8 (in x16) FH/10.5"L slot(s) 2 PCIe 5.0 x8 (in x16) FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Option A* 3 PCIe 5.0 x16 FH/10.5"L double-width slot(s) 1 PCIe 5.0 x16 FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible) Option B* 6 PCIe 5.0 x8 (in x16) FH/10.5"L slot(s) 2 PCIe 5.0 x8 (in x16) FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)
Connectivity	Via AIOM	Via AIOM
VGA/Audio	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 6 bay(s) 6 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) Option A: Total 8 bay(s) 6 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) 2 rear hot-swap 2.5" NVMe* drive bay(s) Option B: Total 10 bay(s) 6 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) 4 rear hot-swap 2.5" NVMe* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110/25110)	Default: Total 6 bay(s) 6 rear hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) Option A: Total 8 bay(s) 6 rear hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) 2 front hot-swap 2.5" NVMe* drive bay(s) Option B: Total 10 bay(s) 6 rear hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) 4 front hot-swap 2.5" NVMe* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110/25110)
Power Supply	2x 2000W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 2000W Redundant (1 + 1) Titanium (certification pending) Level (96%) Hot-plug power supplies
Cooling System	6 counter-rotating 60x60x56mm Fan(s)	6 counter-rotating 60x60x56mm Fan(s)
Form Factor	2U Rackmount	2U Rackmount

# X14 BIGTWIN®

2U 2-Node BigTwin

2U 2-Node BigTwin

**NEW!**  
Intel® Xeon® 6  
Processors  
Supported



MODEL	SYS-622BT-DNC8R	SYS-222BT-DNR
Processor Support	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores
Serverboard	SUPERMICRO X14DBT-B	SUPERMICRO X14DBT-B
Chipset	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM
Expansion Slots	Default 2 PCIe 5.0 x8 LP slot(s) 1 PCIe 5.0 x16 LP slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Default 2 PCIe 5.0 x8 LP slot(s) 1 PCIe 5.0 x16 LP slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)
Connectivity	Via AIOM	Via AIOM
VGA/Audio	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 6 bay(s) 2 front hot-swap 3.5" PCIe 5.0 NVMe/SAS drive bay(s) 4 front hot-swap 3.5" PCIe 4.0 NVMe/SAS drive bay(s) M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default); VROC required for RAID)	Default: Total 12 bay(s) 12 front hot-swap 2.5" PCIe 5.0 NVMe drive bay(s) M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default); VROC required for RAID)
Power Supply	2x 2200W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 2200W Redundant (1 + 1) Titanium Level (96%) power supplies
Cooling System	4x 14.9K RPM Heavy Duty 80x80x38mm Fan(s)	4x 16.5K RPM Heavy Duty 80x80x38mm Fan(s)
Form Factor	2U Rackmount	2U Rackmount

# X14 BIGTWIN®

2U 4-Node BigTwin

2U 4-Node BigTwin

**NEW!**  
Intel® Xeon® 6  
Processors  
Supported



MODEL	SYS-622BT-HNC8R	SYS-222BT-HNC8R
Processor Support	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores
Serverboard	SUPERMICRO® X14DBT-B	SUPERMICRO® X14DBT-B
Chipset	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 16 DIMM slots Max Memory (1DPC): 4TB 6400MT/s ECC DDR5 RDIMM
Expansion Slots	Default 2 PCIe 5.0 x16 LP slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Default 2 PCIe 5.0 x16 LP slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)
Connectivity	Via AIOM	Via AIOM
VGA/Audio	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 3 bay(s) 2 front hot-swap 3.5" PCIe 5.0 NVMe/SAS drive bay(s) 1 front hot-swap 3.5" PCIe 4.0 NVMe/SAS drive bay(s) M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110; VROC required for RAID)	Default: Total 6 bay(s) 2 front hot-swap 2.5" PCIe 5.0 NVMe/SAS drive bay(s) 4 front hot-swap 2.5" PCIe 4.0 NVMe/SAS drive bay(s) M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default); VROC required for RAID)
Power Supply	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies
Cooling System	4x 14.9K RPM Heavy Duty 80x80x38mm Fan(s)	4x 16K RPM Counter Rotating 80x80x56mm Fan(s)
Form Factor	2U Rackmount	2U Rackmount

# X14 BIGTWIN®

2U 4-Node BigTwin

2U 4-Node BigTwin

2U 4-Node BigTwin

**NEW!**  
Intel® Xeon® 6  
Processors  
Supported



MODEL	SYS-222BT-HNC9R	SYS-222BT-HNR	SYS-222BT-HER
Processor Support	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores
Serverboard	SUPER● X14DBT-B	SUPER● X14DBT-B	SUPER● X14DBT-B
Chipset	System on Chip	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM
Expansion Slots	Default 1 PCIe 5.0 x16 LP slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Default 2 PCIe 5.0 x16 LP slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Default 2 PCIe 5.0 x16 LP slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)
Connectivity	Via AIOM	Via AIOM	Via AIOM
VGA/Audio	1 VGA port(s)	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 6 bay(s) 2 front hot-swap 2.5" PCIe 5.0 NVMe/SAS drive bay(s) 4 front hot-swap 2.5" PCIe 4.0 NVMe/SAS drive bay(s) M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default); VROC required for RAID)	Default: Total 6 bay(s) 6 front hot-swap 2.5" PCIe 5.0 NVMe drive bay(s) M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default); VROC required for RAID)	Default: Total 8 bay(s) 8 front hot-swap E3.5 1T PCIe 5.0 NVMe drive bay(s) M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default); VROC required for RAID)
Power Supply	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies
Cooling System	4x 16K RPM Counter Rotating 80x80x56mm Fan(s)	4x 16K RPM Counter Rotating 80x80x56mm Fan(s)	4x 16K RPM Counter Rotating 80x80x56mm Fan(s)
Form Factor	2U Rackmount	2U Rackmount	2U Rackmount

# X14 GRANDTWIN®

2U 4-Node GrandTwin® (Front I/O)

2U 4-Node GrandTwin® (Rear I/O)



**NEW!**

Intel® Xeon® 6 Processors Supported



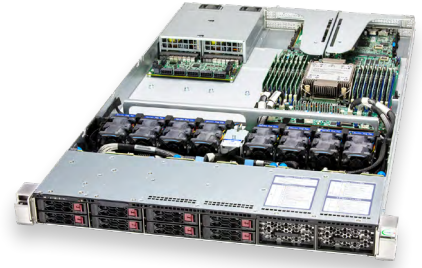
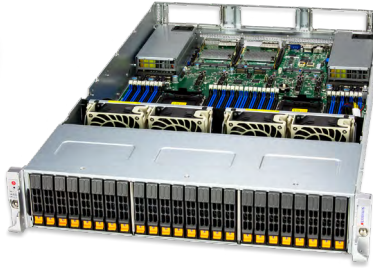
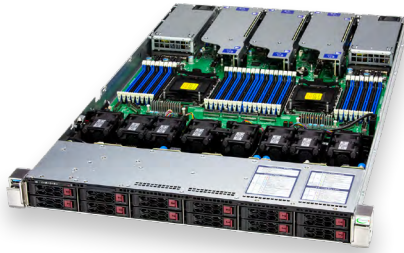
MODEL	SYS-212GT-HNF	SYS-212GT-HNR
Processor Support	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache
Serverboard	SUPERMICRO X14SBT-G	SUPERMICRO X14SBT-G
Chipset	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 16 DIMM slots/2 Channels Max Memory (2DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 16 DIMM slots/2 Channels Max Memory (2DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM
Expansion Slots	Default* 1 PCIe 5.0 x16 LP slot(s) *Optional	Default 2 PCIe 5.0 x16 (in x16) AIOM slot(s) (OCP 3.0 compatible)
Connectivity	Via IO Module	Via IO Module
VGA/Audio	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); KVM with dedicated LAN; IPMI 2.0; TAS; Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); KVM with dedicated LAN; IPMI 2.0; TAS; Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 8 bay(s) 8 front hot-swap E1.S PCIe 5.0 x4 NVMe* drive bay(s) Option A: Total 4 bay(s) 4 front hot-swap E1.S PCIe 5.0 x4 NVMe* drive bay(s) Option B: Total 4 bay(s) 4 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) Option C: Total 2 bay(s) 2 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default)/2280; VROC required for RAID)	Default: Total 6 bay(s) 6 front hot-swap 2.5" PCIe 5.0 x4 NVMe drive bay(s) M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default)/2280; VROC required for RAID)
Power Supply	2x 3000W Redundant (1 + 1) Titanium (certification pending) Level (96%) power supplies	2x 2200W Redundant (1 + 1) Titanium Level (96%) power supplies
Cooling System	2x 16K RPM Heavy Duty 8cm Fan(s)	2x 16K RPM Heavy Duty 8cm Fan(s)
Form Factor	2U Rackmount	2U Rackmount

# X14 CLOUDDC WITH DC-MHS

1U DP CloudDC (SP)

2U DP CloudDC (SP)

1U UP CloudDC (SP)  
12 hot-swap 2.5"



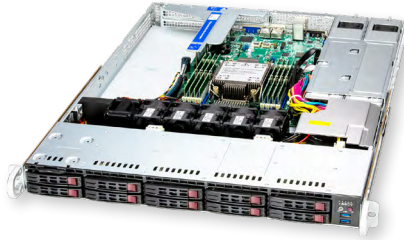
MODEL	SYS-122C-TN	SYS-222C-TN	SYS-112C-TN
Processor Support	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache
Serverboard	SUPER® X14DBHM	SUPER® X14DBHM	SUPER® X14SBHM
Chipset	System on Chip	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 32 DIMM slots Max Memory (2DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 32 DIMM slots Max Memory (2DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 16 DIMM slots/8 Channels Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM Max Memory (2DPC): Up to 1TB 5200MT/s ECC DDR5 RDIMM
Expansion Slots	Default 2 PCIe 5.0 x16 LP slot(s) 1 PCIe 5.0 x8 LP slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Default 4 PCIe 5.0 x16 (in x16) FHFL slot(s) 1 PCIe 5.0 x8 (in x16) FHFL slot(s) Option A 2 PCIe 5.0 x16 (in x16) FHFL slot(s) 1 PCIe 5.0 x8 (in x16) FHFL slot(s)	Default 2 PCIe 5.0 x16 FHFL slot(s) 1 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)
Connectivity	Via Slim-AIOM	Via Slim-AIOM	Via Slim-AIOM
VGA/Audio	1 VGA port(s) (Rear)	1 VGA port(s) (Rear)	1 Mini-DP port(s) (Rear)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 12 bay(s) 12 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default)/2280; VROC required for RAID)	Default: Total 12 bay(s) 12 front hot-swap 2.5" NVMe*/SAS*/SATA* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x4 NVMe slot(s) (M-key 22110(default)/2280; VROC required for RAID)	Default: Total 8 bay(s) 8 front hot-swap 2.5" PCIe 5.0 NVMe/SAS*/SATA* drive bay(s) Option A: Total 12 bay(s) 12 front hot-swap 2.5" PCIe 5.0 NVMe*/SAS*/SATA* drive bay(s) *Optional
Power Supply	2x 1000W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 2000W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 1000W Redundant (1 + 1) Titanium Level (96%) power supplies
Cooling System	8x 4cm heavy duty fans with optimal fan speed control	4x 8cm heavy duty fans with optimal fan speed control	8 Counter-Rotating PWM 40x40x56mm Fan(s)
Form Factor	1U Rackmount	2U Rackmount	1U Rackmount

# X14 UP WIO

1U UP WIO

1U UP WIO

2U UP WIO



MODEL	SYS-112B-WR	SYS-512B-WR	SYS-522B-WR
Processor Support	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache
Serverboard	SUPERMICRO® X145BW-F	SUPERMICRO® X145BW-F	SUPERMICRO® X145BW-F
Chipset	System on Chip	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 8 DIMM slots/8 Channels Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 8 DIMM slots/8 Channels Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 8 DIMM slots/8 Channels Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM
Expansion Slots	Default 2 PCIe 5.0 x16 FHFL slot(s) 1 PCIe 5.0 x8 (in x16) LP slot(s)	Default 2 PCIe 5.0 x16 FHFL slot(s) 1 PCIe 5.0 x8 (in x16) LP slot(s)	Default 1 PCIe 5.0 x16 FHFL double-width slot(s) 1 PCIe 5.0 x16 FHFL slot(s) 2 PCIe 5.0 x8 LP slot(s) Option A* 1 PCIe 5.0 x16 FHFL double-width slot(s) 2 PCIe 5.0 x8 (in x16) FHFL slot(s) 2 PCIe 5.0 x8 LP slot(s)
Connectivity	2 RJ45 1GbE with Intel® I210	2 RJ45 1GbE with Intel® I210	2 RJ45 1GbE with Intel® I210
VGA/Audio	1 VGA port(s)	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 8 bay(s) 8 front hot-swap 2.5" SATA drive bay(s) Option A: Total 10 bay(s) 8 front hot-swap 2.5" SATA drive bay(s) 2 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) Option B: Total 10 bay(s) 4 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) 6 front hot-swap 2.5" SATA drive bay(s) Option C: Total 10 bay(s) 8 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) 2 front hot-swap 2.5" SATA drive bay(s) Option D: Total 10 bay(s) 10 front hot-swap 2.5" SAS* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110; VROC required for RAID)	Default: Total 4 bay(s) 4 front hot-swap 3.5" SATA drive bay(s) Option A: Total 4 bay(s) 4 front hot-swap 2.5" PCIe 5.0 x2 NVMe* drive bay(s) Option B: Total 4 bay(s) 4 front hot-swap 3.5"/2.5" SAS* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110)	Default: Total 8 bay(s) 8 front hot-swap 3.5" SATA drive bay(s) Option A: Total 8 bay(s) 4 front hot-swap 2.5" PCIe 5.0 x4 NVMe* drive bay(s) 4 front hot-swap 3.5"/2.5" SATA drive bay(s) Option B: Total 8 bay(s) 8 front hot-swap 3.5"/2.5" SAS* drive bay(s) *Optional M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110; VROC required for RAID)
Power Supply	2x 860W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 860W Redundant (1 + 1) Titanium Level (96%) power supplies	2x 1000W Redundant (1 + 1) Titanium Level (96%) power supplies
Cooling System	1 AOC cooling Fan(s) (optional) 5 middle cooling PWM 40x40x56mm Fan(s)	1 AOC cooling Fan(s) (optional) 5 middle cooling PWM 40x40x56mm Fan(s)	3x (80cm x80cm x38cm) heavy duty fans with optimal fan speed control
Form Factor	1U Rackmount	1U Rackmount	2U Rackmount

# X14 Petascale

(For Complete System Only)

**NEW!**

Intel® Xeon® 6 Processors Supported



MODEL	SSG-122B-NE316R	SSG-222B-NE3X24R
Processor Support	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache per CPU	Dual Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 108MB Cache per CPU
Serverboard	SUPER <sup>®</sup> X14DBHM	SUPER <sup>®</sup> X14DBHM
Chipset	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 32 DIMM slots Max Memory (2DPC): Up to 8TB 6400MT/s ECC DDR5 RDIMM/LRDIMM	Slot Count: 32 DIMM slots Max Memory (2DPC): Up to 8TB 6400MT/s ECC DDR5 RDIMM/LRDIMM
Expansion Slots	Default 2 PCIe 5.0 x16 FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible)	Default 2 PCIe 5.0 x16 FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible) Option A 1 PCIe 5.0 x8 FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible) Option B 1 PCIe 5.0 x8 FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible) Option C 2 PCIe 5.0 x16 FHHL slot(s) 2 PCIe 5.0 x16 AIOM slot(s) (OCP 3.0 compatible) 1 PCIe 5.0 x8 FHHL slot(s)
Onboard Storage Controller		
Connectivity		
VGA/Audio	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Supermicro Update Manager (SUM); Supermicro SuperDoctor® 5 (SD5); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 16 bay(s) 16 front hot-swap E3.S 1T NVMe drive bay(s) M2: 2 M.2 NVMe/SATA slot(s) (M-key 2280/22110)	Default: Total 24 bay(s) 24 front hot-swap E3.S 1T PCIe 5.0 x4 NVMe drive bay(s) Option A: Total 32 bay(s) 32 front hot-swap E3.S 1T PCIe 5.0 x4 NVMe drive bay(s) Option B: Total 24 bay(s) 16 front hot-swap E3.S 1T PCIe 5.0 x4 NVMe drive bay(s) 8 front fixed E3.S 2T PCIe 5.0 x8 CXL Type 3 drive bay(s) Option C: Total 16 bay(s) 8 front hot-swap E3.S 1T PCIe 5.0 x4 NVMe drive bay(s) 8 front fixed E3.S 2T PCIe 5.0 x8 CXL Type 3 drive bay(s) M2: 2 M.2 NVMe/SATA slot(s) (M-key 2280/22110)
Peripheral Bays	N/A	N/A
Power Supply	2x 2000W Redundant Titanium Level power supplies	2x 2000W Redundant (1 + 1) Titanium Level power supplies
Cooling System	8x 4cm heavy duty fans with optimal fan speed control	4x 8cm heavy duty fans with optimal fan speed control
Form Factor	Rackmount	Rackmount



# X14 TELCO/EDGE

1U UP Short-Depth

1U UP Short-Depth

**NEW!**

Intel® Xeon® 6 Processors Supported



MODEL	SYS-112B-FWT	SYS-112B-FDWR
Processor Support	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/160T; Up to 60MB Cache	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/160T; Up to 60MB Cache
Serverboard	SUPER <sup>®</sup> X14SBW-TF	SUPER <sup>®</sup> X14SBW-F
Chipset	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 8 DIMM slots/8 Channels Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM	Slot Count: 8 DIMM slots/8 Channels Max Memory (1DPC): Up to 1TB 6400MT/s ECC DDR5 RDIMM
Expansion Slots	Default 2 PCIe 5.0 x16 FHFL slot(s) 1 PCIe 5.0 x8 LP slot(s)	Default 2 PCIe 5.0 x16 FHFL slot(s) 1 PCIe 5.0 x8 LP slot(s)
Connectivity	2 RJ45 10GbE with Intel® X550	2 RJ45 1GbE with Intel® I210
VGA/Audio	1 VGA port(s)	1 VGA port(s)
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 2 bay(s) 2 internal fixed 2.5" NVMe/SATA drive bay(s) M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110)	Default: Total 2 bay(s) 2 internal fixed 2.5" NVMe/SATA drive bay(s) M2: 2 M.2 PCIe 5.0 x2 NVMe slot(s) (M-key 2280/22110)
Power Supply	2x 860W Redundant (1 + 1) Titanium Level (96%) Hot-plug power supplies	2x 600W Redundant (1 + 1) Typical 90%+ Level (92%) power supplies
Cooling System	6x 4cm heavy duty fans with optimal fan speed control	6x 4cm heavy duty fans with optimal fan speed control
Form Factor	1U Rackmount	1U Rackmount

# X14 TELCO/EDGE

2U UP Short-Depth

2U UP Short-Depth

**NEW!**

Intel® Xeon® 6 Processors Supported

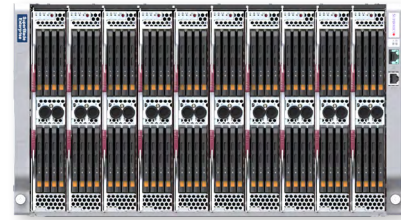
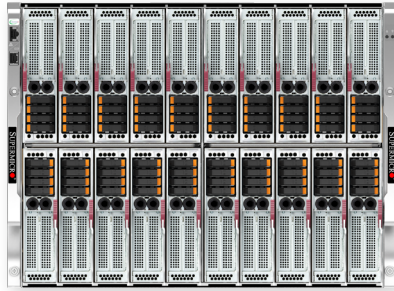


MODEL	SYS-212B-FN2T	SYS-212B-FN4TP
Processor Support	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores	Single Socket E2 (LGA-4710) Intel® Xeon® 6 6700 series processors with E-cores Up to 144C/144T; Up to 172MB Cache
Serverboard	SUPER® X145BM-TFX145BM-TF	SUPER® X145BM-TP4F
Chipset	System on Chip	System on Chip
System Memory (Max.)	Slot Count: 8 DIMM slots Max Memory (1DPC): Up to 1TB ECC DDR5 RDIMM	Slot Count: 8 DIMM slots Max Memory (2DPC): Up to 1TB ECC DDR5 RDIMM
Expansion Slots	Default* 2 PCIe 5.0 x16 (in x16) FHHL slot(s) 1 PCIe 5.0 x16 (in x16) HHHL slot(s) 1 PCIe 5.0 x8 (in x8) HHHL slot(s) Option A* 3 PCIe 5.0 x16 (in x16) FHHL slot(s) 1 PCIe 5.0 x8 (in x8) HHHL slot(s) 1 PCIe 5.0 x8 (in x8) FHHL slot(s) Option B* 3 PCIe 5.0 x16 (in x16) FHHL slot(s) 1 PCIe 5.0 x16 (in x16) HHHL slot(s) 1 PCIe 5.0 x8 (in x8) HHHL slot(s) *Optional	Default 2 PCIe 5.0 x16 FHHL slot(s) 1 PCIe 5.0 x16 HHHL slot(s) 1 PCIe 5.0 x8 HHHL slot(s) Option A* 3 PCIe 5.0 x16 FHHL slot(s) 1 PCIe 5.0 x16 HHHL slot(s) 1 PCIe 5.0 x8 FHHL slot(s) Option B* 3 PCIe 5.0 x16 FHHL slot(s) 2 PCIe 5.0 x16 HHHL slot(s) 1 PCIe 5.0 x8 HHHL slot(s)
Connectivity	2 RJ45 10GBASE-T with Intel® X710-AT2	2 RJ45 10GBASE-T with Intel® X710-TM4 2 SFP+ 10GbE with Intel® X710-TM4
VGA/Audio	1 VGA port	1 VGA port
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); TAS: Supermicro Thin-Agent Service (TAS); SAA(new!)
Drive Bays	Default: Total 2 bay(s) 2 front hot-swap 2.5" NVMe* drive bay(s) *Optional M2: 2 M.2 NVMe slot(s) (M-key 2280/22110)	Default: Total 2 bay(s) 2 front hot-swap 2.5" NVMe drive bay(s) M2: 2 M.2 NVMe slot(s) (M-key 2280/22110)
Power Supply	2x 800W Redundant (1 + 1) power supplies	2x 800W Redundant (1 + 1) power supplies
Cooling System	4x 4-PIN PWM 8cm Fan(s)	4x 4-PIN PWM 8cm Fan(s)
Form Factor	2U Rackmount	2U Rackmount

# X14 SUPERBLADE®

8U Enclosure

6U Enclosure



MODEL	SBE-820H2/J2-830/630 SBE-820H2-822/622 SBE-820J2-822/622/422	SBE-610J2-830/630/430 SBE-610J2-822/622/422
Server	Up to 20 hot-swappable, half-height, single-wide blade servers. Up to 10 hot-swappable, half-height, double-wide blade servers Mixed configuration supported	Up to 10 hot-swappable, single-wide blade servers. Up to 5 hot-swappable, double-wide blade servers Mixed configuration supported
LED Indicator	Power LED, Fault LED	Power LED, Fault LED
Infiniband Switch	200G HDR InfiniBand switch	N/A
Ethernet Switch / Pass-Thru Module	Up to 4 hot-swappable 25G Ethernet switches or pass-thru modules	Up to 4 hot-swappable 25G Ethernet switches or pass-thru modules
Chassis Management Module (CMM)	Up to 2 hot-swappable CMMs for remote system management with software	Up to 2 hot-swappable CMMs for remote system management with software
Models	SBE-820H2/ J2- 830/630: Up to 8 hot-swappable 3000W Titanium (96% efficiency) power supplies  SBE-820H2- 822/622: Up to 8 hot-swappable 2200W Titanium (96% efficiency) power supplies  SBE-820J2- 822/ 622/ 422: Up to 8 hot-swappable 2200W Titanium (96% efficiency) power supplies	SBE-610J2-830/ 630/430: Up to 8 hot-swappable 3000W Titanium (96% efficiency) power supplies  SBE-610J2- 822/ 622/ 422: Up to 8 hot-swappable 2200W Titanium (96% efficiency) power supplies
Rack Unit	8 RU	6 RU
Form Factor	356 x 447 x 813mm (14" x 17.6" x 32")	267 x 447 x 813mm (10.5" x 17.6" x 32")

# X14 8U SUPERBLADE®

20 DP Nodes in 8U

10 DP Nodes in 8U



MODEL	SBI-422B-1NE14	SBI-422B-5NE14
Servers per Enclosure	20	10
Processor	Dual Intel® Xeon® 6700 series processors with E-cores - up to 288 cores per node	Dual Intel® Xeon® 6700 series processors with E-cores - up to 288 cores per node
System Memory (Max.)	Support for DDR5-6400 with up to 16 DIMMs (up to 4TB memory)	Support for DDR5-6400 with up to 16 DIMMs (up to 4TB memory)
PCIe Expansion	2 OCP 3.0 (PCIe 5.0 x16)	2 OCP 3.0 (PCIe 5.0 x16)
Storage & RAID	4 Hot-swappable E1.S NVMe SSDs 1 M.2 NVMe SSD Additional 4 M.2 NVMe SSDs with optional mezzanine card	4 Hot-swappable E1.S NVMe SSDs 1 M.2 NVMe SSD Additional 4 M.2 NVMe SSDs with optional mezzanine card
Networking	Dual-port 25GbE LOM (LAN on Motherboard) OCP 3.0 slots for up to 2 network cards Optional mezzanine card for 200G IB or additional dual-port 25GbE	Dual-port 25GbE LOM (LAN on Motherboard) OCP 3.0 slots for up to 2 network cards Optional mezzanine card for 200G IB or additional dual-port 25GbE
Management	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust
LED Indicators	Fault LED, Network Activity LED, Power LED, UID	Fault LED, Network Activity LED, Power LED, UID
Form Factor	165 x 44.4 x 597mm (6.5" x 1.75" x 23.5")	165 x 88.9 x 597mm (6.5" x 3.5" x 23.5")
Enclosure	SBE-820H2/J2-830/630 SBE-820H2-822/622 SBE-820H-822/622 SBE-820J2-822/622 SBE-820J-822/622/422	SBE-820H2/J2-830/630 SBE-820H2/J2-822/622

# X14 6U SUPERBLADE®

10 UP Nodes in 6U

5 UP Nodes in 6U

10 UP Nodes in 6U

**NEW!**  
Intel® Xeon® 6  
Processors  
Supported



MODEL	SBI-612B-1NE34	SBI-612B-5NE34	SBI-612B-1C2N
Servers per Enclosure	10	5	10
Processor	Single Intel® Xeon® 6700 series processors	Single Intel® Xeon® 6700 series processors	Single Intel® Xeon® 6700 series processors
GPU or Network Cards	Up to 2 FHFL GPUs or network cards	Up to 4 FHFL GPUs or network cards	Up to 2 FHFL GPUs or network cards
System Memory (Max.)	Support for DDR5-6400 with 16 DIMMs in UP (Up to 4TB memory)	Support for DDR5-6400 with 16 DIMMs in UP (Up to 4TB memory)	Support for DDR5-6400 with 16 DIMMs in UP (Up to 4TB memory)
PCIe Expansion	Up to 2 PCIe 5.0 x16 slots (Front I/O)	Up to 4 PCIe 5.0 x16 slots (Front I/O)	Up to 2 PCIe 5.0 x16 slots (Front I/O)
Storage & RAID	4 Hot-swappable E3.S NVMe SSDs 1 M.2 NVMe SSD	4 Hot-swappable E3.S NVMe SSDs 1 M.2 NVMe SSD	2 Hot-swappable U.2 NVMe/SAS 1 M.2 NVMe SSD
Networking	Dual-port 25GbE LOM (LAN on Motherboard) 2 PCIe network cards (Front I/O) Optional mezzanine card for additional dual-port 25GbE	Dual-port 25GbE LOM (LAN on Motherboard) 4 PCIe network cards (Front I/O) Optional mezzanine card for additional dual-port 25GbE	Dual-port 25GbE LOM (LAN on Motherboard) 2 PCIe network cards (Front I/O) Optional mezzanine card for additional dual-port 25GbE
Management	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust
LED Indicators	Fault LED, Network Activity LED, Power LED, UID	Fault LED, Network Activity LED, Power LED, UID	Fault LED, Network Activity LED, Power LED, UID
Form Factor	248 x 44.4 x 597mm (9.75" x 1.75" x 23.5")	248 x 88.9 x 596.9mm (9.75" x 3.5" x 23.5")	248 x 44.4 x 597mm (9.75" x 1.75" x 23.5")
Enclosure	SBE-610J2-830/630/430 SBE-610J2-822/622/422 SBE-610J-822/622/422	SBE-610J2-830/630/430 SBE-610J2-822/622/422	SBE-610J2-830/630/430 SBE-610J2-822/622/422 SBE-610J-822/622/422

# X14 6U SUPERBLADE®

10 DP Nodes in 6U

5 DP Nodes in 6U

10 DP Nodes in 6U

5 DP Nodes in 6U



MODEL	SBI-622B-1NE34	SBI-622B-5NE34	SBI-622B-1NE38	SBI-622B-5NE38
Servers per Enclosure	10	5	10	5
Processor	Dual Intel® Xeon® 6700 series processors	Dual Intel® Xeon® 6700 series processors	Dual Intel® Xeon® 6700 series processors	Dual Intel® Xeon® 6700 series processors
GPU or Network Cards	Up to 2 FHHL GPUs and network cards	Up to 4 GPUs or network cards	N/A	N/A
System Memory (Max.)	Support for DDR5-6400 with 32 DIMMs in DP (Up to 8TB memory)	Support for DDR5-6400 with 32 DIMMs in DP (Up to 8TB memory)	Support for DDR5-6400 with 32 DIMMs in DP (Up to 8TB memory)	Support for DDR5-6400 with 32 DIMMs in DP (Up to 8TB memory)
PCIe Expansion	Up to 2 PCIe 5.0 x16 slots (Front I/O)	Up to 4 PCIe 5.0 slots (Front I/O)	N/A	N/A
Storage & RAID	4 Hot-swappable E3.S NVMe SSDs 2 M.2 NVMe SSDs with optional adapter	4 Hot-swappable E3.S NVMe SSDs 2 M.2 NVMe SSDs with optional adapter	8 Hot-swappable E3.S NVMe SSDs 2 M.2 NVMe SSDs with optional adapter	8 Hot-swappable E3.S NVMe SSDs 2 M.2 NVMe SSDs with optional adapter
Networking	Dual-port 25GbE LOM (LAN on Motherboard) 2 PCIe network cards (Front I/O) Optional mezzanine card for additional dual-port 25GbE	Dual-port 25GbE LOM (LAN on Motherboard) 4 PCIe network cards (Front I/O) Optional mezzanine card for additional dual-port 25GbE	Dual-port 25GbE LOM (LAN on Motherboard) Optional mezzanine card for additional dual-port 25GbE	Dual-port 25GbE LOM (LAN on Motherboard) Optional mezzanine card for additional dual-port 25GbE
Management	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust	Redundant Chassis Management Modules, Open Industry Standard IPMI 2.0 / KVM over IP / Redfish API / TPM 2.0 / Signed Firmware / Hardware Root of Trust
LED Indicators	Fault LED, Network Activity LED, Power LED, UID	Fault LED, Network Activity LED, Power LED, UID	Fault LED, Network Activity LED, Power LED, UID	Fault LED, Network Activity LED, Power LED, UID
Form Factor	248 x 44.4 x 597mm (9.75" x 1.75" x 23.5")	248 x 88.9 x 596.9mm (9.75" x 3.5" x 23.5")	248 x 44.4 x 597mm (9.75" x 1.75" x 23.5")	248 x 88.9 x 596.9mm (9.75" x 3.5" x 23.5")
Enclosure	SBE-610J2-830/630/430 SBE-610J2-822/622/422 SBE-610J-822/622/422	SBE-610J2-830/630/430 SBE-610J2- 822/622/422	SBE-610J2-830/630/430 SBE-610J2- 822/622/422 SBE-610J-822/622/422	SBE-610J2-830/630/430 SBE-610J2-822/622/422



# Global Expansion

Providing Greater Economies of Scale and Accelerated Support to Data Center, Cloud Computing, AI, Enterprise IT, HPC, 5G, Hyperscale, and Embedded Solutions Customers Worldwide



**Worldwide Headquarters**  
San Jose, California, USA



## America

- Supermicro's Headquarters expansion: Over 1.5 million square foot **Green Computing Park** in San Jose, California signals the company's increasing leadership in the IT industry
- One of the largest high-tech R&D, manufacturing, and business hubs in Silicon Valley
- East Coast Sales and Service Office



## APAC

Supermicro's **Asia Science and Technology Park** is a key milestone in the company's growth as a true global leader in the development of advanced, power saving computing technologies



## Silicon Valley

Expanded manufacturing, command center



## EMEA

Supermicro's system integration facility and services in The Netherlands serves the dynamic, rapidly growing EMEA market with localized supply and time-to-market advantages

## Supermicro Worldwide

### Worldwide Headquarters

Super Micro Computer, Inc.  
980 Rock Avenue, San Jose, CA 95131 USA  
Tel: +1-408-503-8000  
Fax: +1-408-503-8008  
General Info: [Marketing@Supermicro.com](mailto:Marketing@Supermicro.com)  
Tech Support: [Support@Supermicro.com](mailto:Support@Supermicro.com)  
Webmaster: [Webmaster@Supermicro.com](mailto:Webmaster@Supermicro.com)

### European Branch

Super Micro Computer, B.V.  
Het Sterrenbeeld 28, 5215 ML,  
's-Hertogenbosch, The Netherlands  
Tel: +31-73-640-0390  
Fax: +31-73-641-6525  
General Info: [Sales\\_Europe@supermicro.com](mailto:Sales_Europe@supermicro.com)  
Support: [Support\\_Europe@supermicro.com](mailto:Support_Europe@supermicro.com)

### Taiwan Office

Super Micro Computer, Inc.  
3F., No.150, Jian 1st Rd., Zhonghe Dist.,  
Taoyuan City 334, Taiwan (R.O.C.)  
Tel: +886-2-8226-3990  
Fax: +886-2-8226-3992  
Support: [Support@Supermicro.com.tw](mailto:Support@Supermicro.com.tw)

### Beijing, China Office

Supermicro Technology (Beijing) Co., Ltd  
Suite 701, Tower D, Jiahua Building,  
No.9, Shangdi 3rd Street,  
Haidian District, 100085,  
Beijing, China  
Tel: +86-10-62969165  
E-mail: [Sales-CN@supermicro.com](mailto:Sales-CN@supermicro.com)

### Japan Office

Supermicro Japan  
21F Shibuya Infos Tower, 20-1,  
Sakuragaoka-cho, Shibuya-Ku, Tokyo,  
150-0031 Japan  
Tel: +81-3-5728-5196  
Fax: +81-3-5728-5197  
Sales inquiry: [Sales\\_Inquiry\\_JP@Supermicro.com](mailto:Sales_Inquiry_JP@Supermicro.com)  
Tech Support: [Support\\_Japan@Supermicro.com](mailto:Support_Japan@Supermicro.com)

### U.S. East Coast Office

Super Micro Computer, Inc.  
525 Washington Blvd, 20th Floor  
Jersey City, NJ 07310 USA  
General Info: [Marketing@Supermicro.com](mailto:Marketing@Supermicro.com)

### U.K. Sales Office

Super Micro Computer, B.V.  
Regus - Reading Green Park  
200 Brook Drive, Green Park, Reading  
Berkshire, England, RG2 6UB, UK  
Tel: +31-73-640-0390 Ext. 2800  
General Info: [Sales\\_Europe@supermicro.com](mailto:Sales_Europe@supermicro.com)  
Tech Support: [Support\\_Europe@Supermicro.com](mailto:Support_Europe@Supermicro.com)

### Supermicro Science & Technology Park

Super Micro Computer, Inc.  
No.1899, Xingfeng Rd., Bade Dist.,  
Taoyuan City 334, Taiwan (R.O.C.)  
Tel: +886-2-8226-3990  
Fax: +886-3-362-8266  
Support: [Support@Supermicro.com.tw](mailto:Support@Supermicro.com.tw)

### Shanghai, China Office

Super Micro Computer, Inc.  
Room 702, No 398, North Caoxi Road,  
Huizhi Building, Xuhui District,  
Shanghai, China 200030  
Tel: +86-21-61152558  
Tech Support: +86-21-61152556  
E-mail: [Sales-CN@supermicro.com](mailto:Sales-CN@supermicro.com)  
Support: [Support-CN@supermicro.com](mailto:Support-CN@supermicro.com)

### Korea Office

Super Micro Computer Holding B.V.  
#1001, Trade Tower, 511, Yeongdong-daero,  
Gangnam-gu, Seoul, Korea, 06164  
Tel: +82-2-554-0045  
Fax: +82-2-554-0146  
Sales Inquiry: [Sales-Asia@supermicro.com.tw](mailto:Sales-Asia@supermicro.com.tw)

# Better

Better AI Performance  
Per Watt and Per Dollar

# Faster

First-to-Market Innovation with the  
Highest Performance AI Server Designs

# Greener

Reduced Environmental  
Impact and Lower TCO



## Worldwide Headquarters

Super Micro Computer, Inc.  
980 Rock Ave.  
San Jose, CA 95131, USA  
Tel: +1-408-503-8000  
Fax: +1-408-503-8008  
E-mail: [Marketing@Supermicro.com](mailto:Marketing@Supermicro.com)

## EMEA Headquarters

Super Micro Computer, B.V.  
Het Sterrenbeeld 28, 5215 ML,  
's-Hertogenbosch, The Netherlands  
Tel: +31-73-640-0390  
Fax: +31-73-641-6525  
E-mail: [Sales\\_Europe@supermicro.com](mailto:Sales_Europe@supermicro.com)

## APAC Headquarters

Super Micro Computer, Taiwan Inc.  
3F, No. 150, Jian 1st Rd., Zhonghe Dist.,  
New Taipei City 235, Taiwan  
Tel: +886-2-8226-3990  
Fax: +886-2-8226-3991  
E-mail: [Marketing@Supermicro.com.tw](mailto:Marketing@Supermicro.com.tw)

[www.supermicro.com](http://www.supermicro.com)

©Super Micro Computer, Inc. Specifications subject to change without notice. All other brands and names are the property of their respective owners. All logos, brand names, campaign statements and product images contained herein are copyrighted and may not be reprinted and/or reproduced, in whole or in part, without express written permission by Supermicro Corporate Marketing.



MKT-0002-06/2024-R36